

IN THE CLAIMS:

Claims 1 through 6 and 9 through 20 are proposed to be amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently amended) A method for forming an interposer substrate, comprising:
providing a rectangular, substantially planar substrate comprising a dielectric material and having a longitudinal axis; and
forming ~~an~~ ~~a~~ ~~first elongated interconnect slot having a longitudinal axis and at least a second elongated~~ ~~multisegmented~~ interconnect slot having a longitudinal axis ~~positioned approximately collinear to the longitudinal axis of the substantially planar substrate~~ ~~including comprising:~~
~~positioning the longitudinal axis of each of the first elongated interconnect slot and the at least a second elongated interconnect slot approximately collinear to the longitudinal centerline of the substrate;~~
~~longitudinally separating the first elongated interconnect slot from the at least a second elongated interconnect slot by forming at least one transversely extending crosspiece; and~~
~~removing dielectric material from the substrate along the longitudinal axis of the substrate and positioning at least one crosspiece substantially transverse to the longitudinal axis of the substrate to form a first segment of the elongated multisegmented interconnect slot and at least a second segment of the elongated multisegmented interconnect slot separated by the at least one crosspiece; and~~
sizing, configuring and positioning the first ~~segment of the elongated~~ ~~multisegmented~~ interconnect slot and the at least a second ~~segment of the elongated~~ ~~multisegmented~~ interconnect slot for respective alignment with a first plurality of

bond pads and at least a second plurality of bond pads on a single semiconductor die to be placed on the substantially planar substrate to enable respective access to the first plurality of bond pads and the at least a second plurality of bond pads through the first segment of the elongated interconnect multisegmented interconnect slot and the at least a second segment of the elongated multisegmented interconnect slot.

2. (Currently amended) The method of claim 1, further comprising forming the first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot by milling through the substrate and forming positioning the at least one transversely extending crosspiece comprising leaving at least one unmilled portion of the substrate lying intermediate opposing, distal ends of the first segment of the elongated multisegmented interconnect slot and the at least a second segment of the elongated multisegmented interconnect slot.

3. (Currently amended) The method of claim 2, further comprising producing filleted side edges on the at least one transversely extending crosspiece during the milling.

4. (Withdrawn-Currently amended) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot comprises forming a unitary elongated interconnect slot and positioning forming the at least one transversely extending crosspiece by bonding a segment of material transversely across the unitary interconnect slot at a location intermediate opposing ends thereof.

5. (Withdrawn-Currently amended) The method of claim 4, wherein positioning forming the at least one transversely extending crosspiece comprises forming a tape segment coated with an adhesive on opposing sides thereof and adhering the tape segment to a surface of the substantially planar substrate.

6. (Withdrawn-Currently amended) The method of claim 1, wherein forming the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~ comprises forming a unitary elongated interconnect slot, forming an "I"-shaped segment of material and bonding a head portion of the "I"-shaped segment to the substrate on one side of the unitary interconnect slot and a foot portion of the "I"-shaped segment to the substrate on an opposing side of the unitary interconnect slot with a body portion of the "I"-shaped segment extending transversely thereacross to form the at least one ~~transversely extending~~ crosspiece.

7. (Withdrawn) The method of claim 6, further comprising forming the "I"-shaped segment as a film having an adhesive coating on opposing sides thereof.

8. (Withdrawn) The method of claim 6, further comprising forming the "I"-shaped segment as a substantially rigid plastic segment.

9. (Withdrawn-Currently amended) The method of claim 1, wherein forming the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~ comprises forming a unitary elongated interconnect slot, forming a "T"-shaped element having a body and a cap, extending the body into the unitary interconnect slot in contact with opposing sides thereof and bonding legs of the cap extending transversely to the unitary interconnect slot over a surface of the substrate thereto to form the at least one ~~transversely extending~~ crosspiece.

10. (Withdrawn-Currently amended) The method of claim 1, wherein forming the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~ comprises forming a unitary elongated interconnect slot, forming a tape segment of a polymeric material containing a reinforcement material, ~~positioning~~ ~~disposing~~ the tape segment transversely across the unitary interconnect slot and bonding the tape segment to a surface of the substrate.

11. (Withdrawn-Currently amended) The method of claim 1, wherein forming the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~ comprises forming a unitary elongated interconnect slot, interposing a bar of material transversely between opposing sides of the unitary interconnect slot and bonding the bar thereto.

12. (Currently amended) The method of claim 1, further comprising forming the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~ to a ~~combined total~~ length of about 67% or more of a length of the substrate.

13. (Currently amended) The method of claim 12, further comprising forming the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~ to a ~~combined total~~ length of about 70 to 80% of a length of the substrate.

14. (Currently amended) The method of claim 1, further comprising ~~locating positioning~~ the at least one ~~transversely extending~~ crosspiece substantially at a longitudinal midpoint of a ~~combined total~~ length of the ~~first elongated interconnect slot and the at least a second elongated multisegmented interconnect slot~~.

15. (Withdrawn-Currently amended) A method for forming an interposer substrate, comprising:
providing a rectangular, substantially planar substrate comprising a dielectric material and having a longitudinal ~~centerline axis~~;
positioning and forming a plurality of ~~an elongated multisegmented interconnect slot with slot~~ and a plurality of crosspieces, comprising a longitudinal axis of each of the plurality of elongated interconnect slots positioned approximately collinear to the longitudinal centerline of the substrate;
~~removing dielectric material from the substrate along the longitudinal axis of the substrate and positioning the plurality of crosspieces substantially transverse to the longitudinal axis of the substrate to form a plurality of segments of the elongated~~

multisegmented interconnect slot and to separate each segment of the plurality of segments from another segment of the plurality of segments;
separating each of the plurality of elongated interconnect slots from at least one other elongated interconnect slot of the plurality by forming a plurality of transversely extending crosspieces;
sizing, configuring and positioning each of the plurality of elongated interconnect slotssegments of the elongated multisegmented slot for respective alignment with a plurality of bond pads on a single semiconductor die to be placed on the substantially planar substrate to enable access to each plurality of bond pads through one of the plurality of segments of the elongated multisegmented interconnect slot of the plurality.

16. (Withdrawn-Currently amended) The method of claim 15, further comprising forming the plurality of elongated multisegmented interconnect slotsslot by milling approximately the same distance through the substrate to form each of the at least a plurality of segments of the elongated multisegmented interconnect slotsslot and positioning forming the plurality of transversely extending crosspieces by leaving a plurality of unmilled portions of the substrate.

17. (Withdrawn-Currently amended) The method of claim 16, further comprising producing filleted side edges on the plurality of transversely extending crosspieces during the milling.

18. (Withdrawn-Currently amended) The method of claim 15, further comprising forming the plurality of segments of the elongated multisegmented interconnect slotsslot to a combined length of about 67% or more of a length of the substrate.

19. (Withdrawn-Currently amended) The method of claim 18, further comprising forming the plurality of segments of the elongated multisegmented interconnect ~~slots~~slot to a combined length of about 70 to 80% of a length of the substrate.

20. (Withdrawn-Currently amended) The method of claim 15, further comprising ~~positioning~~ ~~locating~~ each of the plurality of ~~transversely extending~~ crosspieces approximately equidistant from at least a first longitudinally adjacent crosspiece and one of a second longitudinally adjacent crosspiece and an end of ~~an~~the elongated multisegmented interconnect slot.